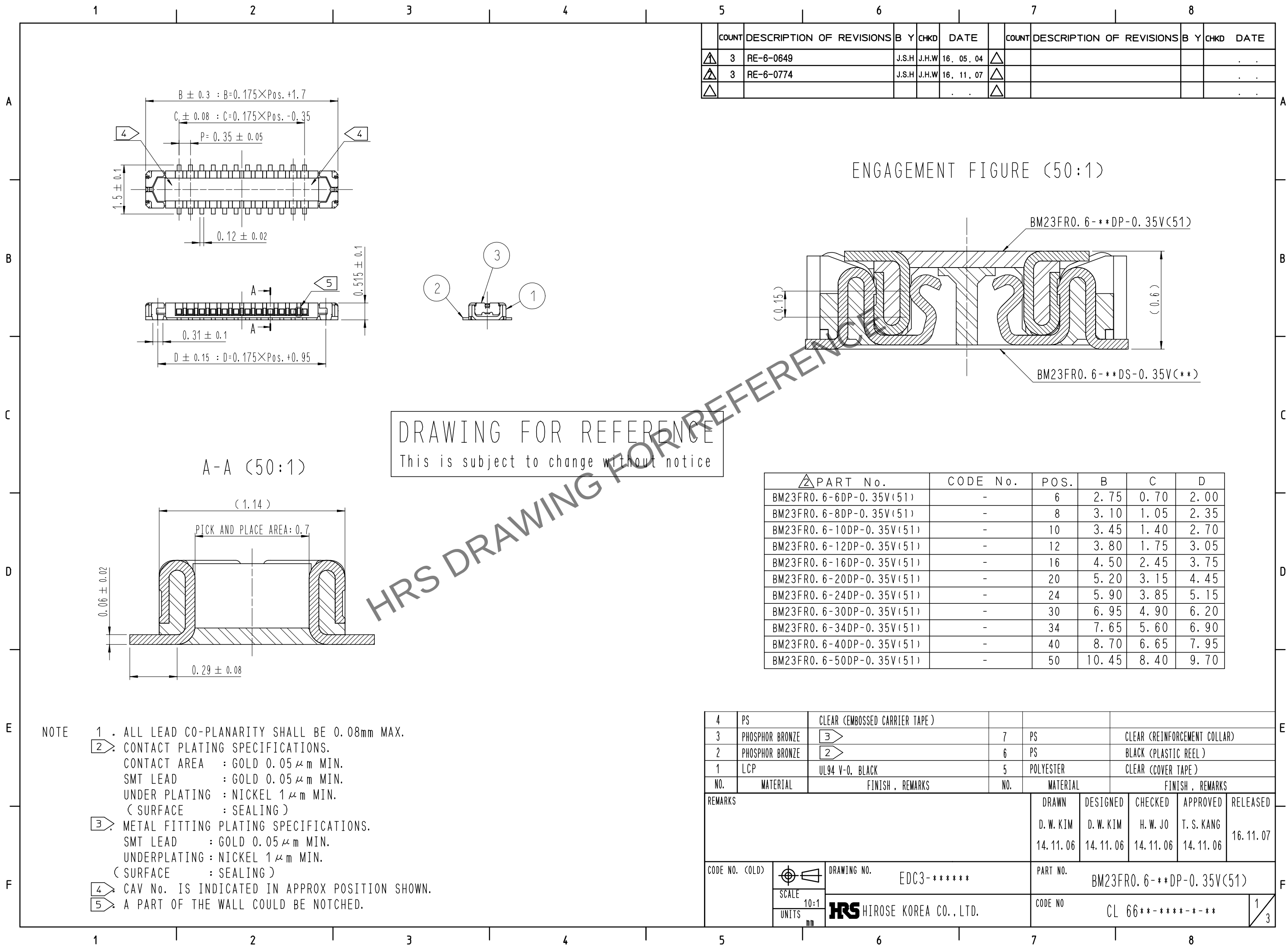
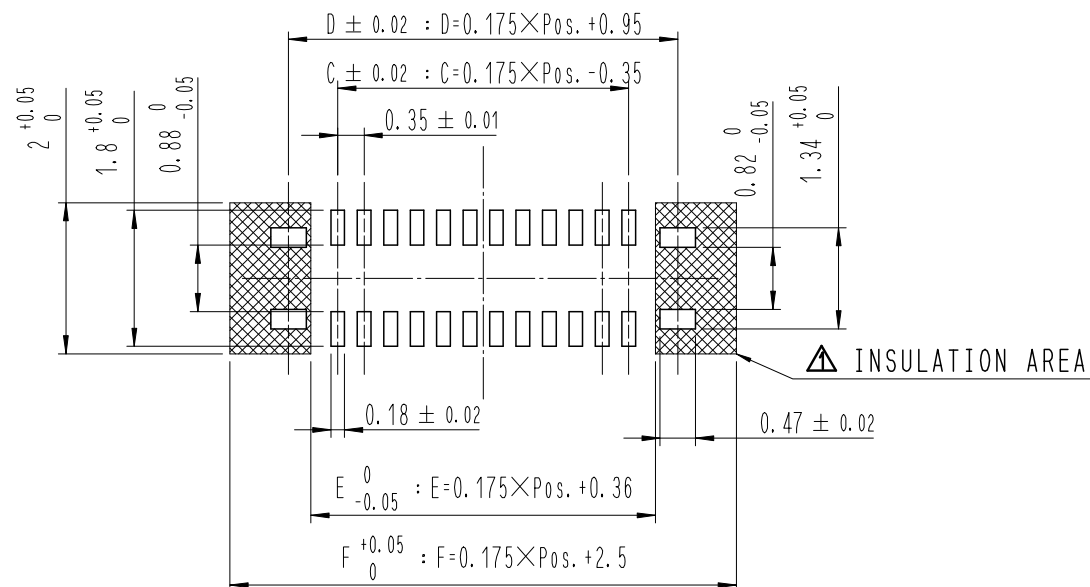


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In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.



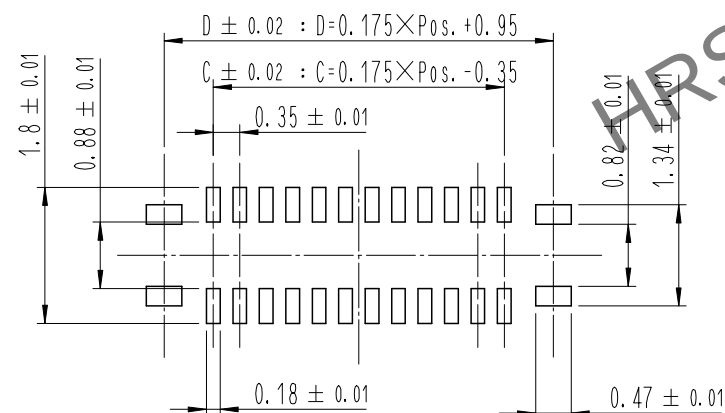
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7 RECOMMENDED PCB LAYOUT



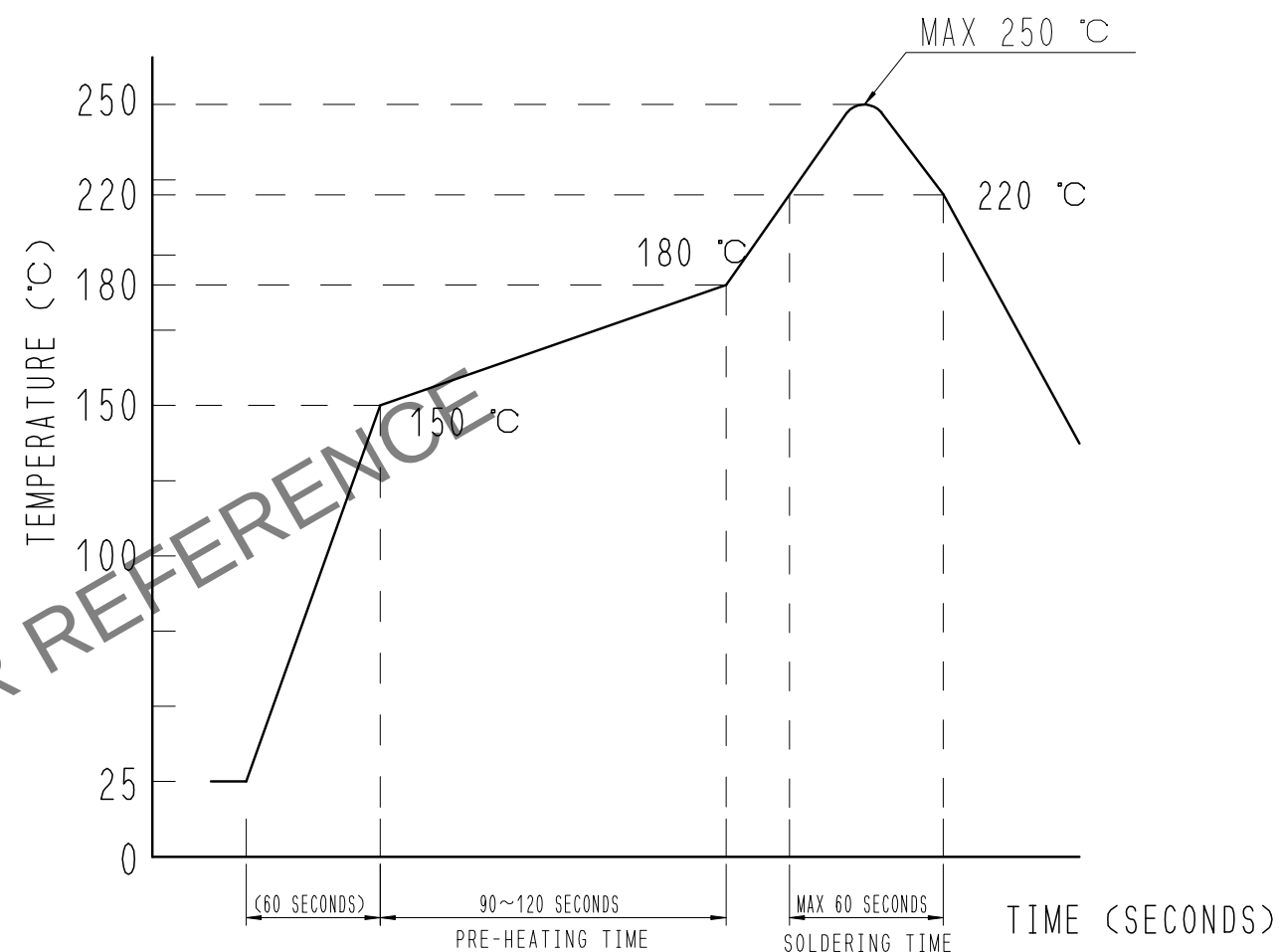
RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



POS.	C	D	E	F
6	0.70	2.00	1.41	3.55
8	1.05	2.35	1.76	3.90
10	1.40	2.70	2.11	4.25
12	1.75	3.05	2.46	4.60
16	2.45	3.75	3.16	5.30
20	3.15	4.45	3.86	6.00
24	3.85	5.15	4.56	6.70
30	4.90	6.20	5.61	7.75
34	5.60	6.90	6.31	8.45
40	6.65	7.95	7.36	9.50
50	8.40	9.70	9.11	11.25

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220 $^{\circ}\text{C}$: 60 SEC MAX.
(PEAK TEMPERATURE: 250 $^{\circ}\text{C}$ MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE (MIN): 150 $^{\circ}\text{C}$
PRE-HEAT TEMPERATURE (MAX): 180 $^{\circ}\text{C}$
PRE-HEAT TIME: 90-120 SEC.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-*****	PART NO.	BM23FR0.6-**DP-0.35V(51)
	SCALE	10:1	CODE NO	CL 66**-*****-***
UNITS	mm	HIROSE KOREA CO., LTD.		2/3

